

Bridgelux® SMD 2835 0.5W 3V

Product Data Sheet DS544



Introduction

Features

- Industry-standard 2835 footprint
- Enables 3- and 6-step MacAdam ellipse custom binning kits
- · RoHS compliant and lead free
- Multiple CCT configurations for a wide range of lighting applications

Benefits

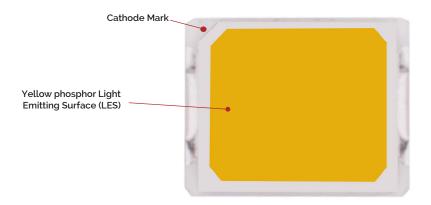
- · Lower operating and manufacturing cost
- Ease of design and rapid go-to-market
- · Uniform, consistent white light
- · Reliable and constant white point
- · Compliant with environmental standards
- Design flexibility

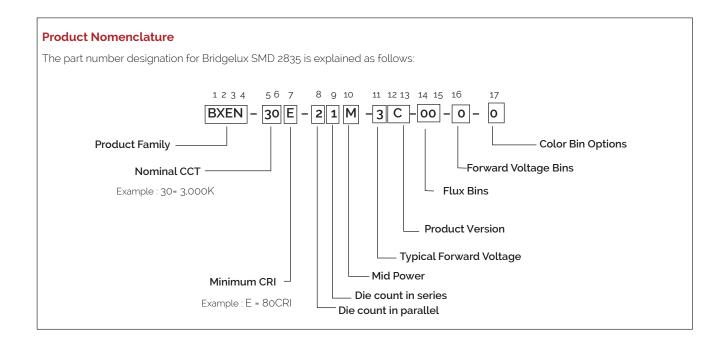
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Product Feature Map

Bridgelux SMD LED products come in industry standard package sizes and follow ANSI binning standards. These LEDs are optimized for cost and performance, helping to ensure highly competitive system lumen per dollar performance while addressing the stringent efficacy and reliability standards required for modern lighting applications.





Product Selection Guide

The following product configurations are available:

Table 1: Selection Guide, Pulsed Measurement Data at 150mA (T_i=T_{sp}=25°C)

Part Number ^{1,6}	Nominal CCT ²	CD13.5		Forward Voltage ^{4, 5} (V)			Typical Pulsed	Typical Power	Typical Efficacy
	(K)		(mA)	Min	Typical	Max	Flux (lm)4.5	(W)	(lm/W)
BXEN-27E-21M-3C-00-0-0	2700	80	150	2.80	2.92	3.20	72.1	0.4	165
BXEN-30E-21M-3C-00-0-0	3000	80	150	2.80	2.92	3.20	74.1	0.4	169
BXEN-35E-21M-3C-00-0-0	3500	80	150	2.80	2.92	3.20	74.1	0.4	169
BXEN-40E-21M-3C-00-0-0	4000	80	150	2.80	2.92	3.20	78.0	0.4	178
BXEN-50E-21M-3C-00-0-0	5000	80	150	2.80	2.92	3.20	78.0	0.4	178
BXEN-57E-21M-3C-00-0-0	5700	80	150	2.80	2.92	3.20	78.0	0.4	178
BXEN-65E-21M-3C-00-0-0	6500	80	150	2.80	2.92	3.20	77.5	0.4	177

Table 2: Selection Guide, Pulsed Test Performance (T_{sp} = 85°C)^{7.8}

Part Number ^{1,6}	Nominal CCT ²	CRI ^{3, 5}	Nominal Drive Current	Forward Voltage ^{4, 5} (V)			Typical Pulsed	Typical Power	Typical Effica-
	(K)		(mA)	Min	Typical	Max	Flux (lm) ^{4.5}	(W)	cy (lm/W)
BXEN-27E-21M-3C-00-0-0	2700	80	150	2.73	2.85	3.13	64.6	0.4	151
BXEN-30E-21M-3C-00-0-0	3000	80	150	2.73	2.85	3.13	66.4	0.4	155
BXEN-35E-21M-3C-00-0-0	3500	80	150	2.73	2.85	3.13	66.4	0.4	155
BXEN-40E-21M-3C-00-0-0	4000	80	150	2.73	2.85	3.13	69.9	0.4	163
BXEN-50E-21M-3C-00-0-0	5000	80	150	2.73	2.85	3.13	69.9	0.4	163
BXEN-57E-21M-3C-00-0-0	5700	80	150	2.73	2.85	3.13	69.9	0.4	163
BXEN-65E-21M-3C-00-0-0	6500	80	150	2.73	2.85	3.13	69.5	0.4	162

Notes for Tables 1 & 2:

- 2. Product CCT is cold targeted at Tsp = 25°C. Nominal CCT as defined by ANSI C78.377-2011.
- 3. Listed CRIs are minimum values and include test tolerance.
- 4. Products tested under pulsed condition (10ms pulse width) at nominal drive current
- 5. Bridgelux maintains a ±7.5% tolerance on luminous flux measurements, ±0.1V tolerance on forward voltage measurements, and ±2 tolerance on CRI measurements for the SMD 2835.
- 6. Refer to Table 5 and Table 6 for Bridgelux SMD 2835 Luminous Flux Binning and Forward Voltage Binning information.
- 7. Typical pulsed test performance values are provided as reference only and are not a guarantee of performance.
- 8. Typical performance is estimated based on operation under pulsed current with LED emitter mounted onto a heat sink with thermal interface material and the solder point temperature maintained at 85°C. Based on Bridgelux test setup, values may vary depending on the thermal design of the luminaire and the exposed environment to which the product is subjected.

^{1.} The last 6 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-0-0" denotes the full distribution of flux, forward voltage, and color bin.

Example: BXEN-30E-21M-3C-00-0-0 refers to the full distribution of flux, forward voltage, and color within a 3000K 6-step ANSI standard chromaticity region with a minimum of 80 CRI, 2x1 die configuration, Mid power, 2.92V typical forward voltage.

Electrical Characteristics

Table 3: Electrical Characteristics

	Part Number Drive Current (mA)		orward Voltaç (V) ^{1,2}	je	Typical Temperature Coefficient	Typical Thermal Resistance Junction to Solder Point ³ R _{j-sp} (°C/W)	
Part Number			Typical	Maximum	of Forward Voltage ∆V ₊ ∕∆T (mV/°C)		
BXEN-XXE-21M-3C-00-0-0	150	2.80	2.92	3.20	-1.13	15	

Notes for Table 3:

- 1. Bridgelux maintains a tolerance of ± 0.1V on forward voltage measurements. Voltage minimum and maximum values at the nominal drive current are guaranteed by 100% test.
- 2. Products tested under pulsed condition (10ms pulse width) at nominal drive current where $Tsp = 25^{\circ}C$.
- 3. Thermal resistance value was calculated using total electrical input power; optical power was not subtracted from input power.

Absolute Maximum Ratings

Table 4: Maximum Ratings

Parameter	Maximum Rating		
LED Junction Temperature (T _j)	125°C		
Storage Temperature	-40°C to +105°C		
Operating Solder Point Temperature (T _{Sp})	-40°C to +105°C		
Soldering Temperature	260°C or lower for a maximum of 10 seconds		
Maximum Drive Current	240mA		
Maximum Peak Pulsed Forward Current ¹	360mA		
Maximum Reverse Voltage²	-		
Moisture Sensitivity Rating	MSL 3		
Electrostatic Discharge	2kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012		

Notes for Table 4:

^{1.} Bridgelux recommends a maximum duty cycle of 10% and pulse width of 10 ms when operating LED SMD at maximum peak pulsed current specified. Maximum peak pulsed current indicate values where LED SMD can be driven without catastrophic failures.

^{2.} Light emitting diodes are not designed to be driven in reverse voltage and will not produce light under this condition. no rating is provided

Product Bin Definitions

Table 5 lists the standard photometric luminous flux bins for Bridgelux SMD 2835 LEDs. Although several bins are listed, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all CCTs.

Table 5: Luminous Flux Bin Definitions at 150mA, $T_{\rm sp}$ =25°C

Bin Code	Minimum	Maximum	Unit	Condition
2D	65	70		
2E	70	75	lm	1 450m A
2F	75	80	ł lm	I _F =150mA
2G	80	85		

Note for Table 5:

1. Bridgelux maintains a tolerance of \pm 7.5% on luminous flux measurements.

Table 6: Forward Voltage Bin Definition at 150mA, T_{sp} =25 $^{\circ}$ C

Bin Code	Minimum	Maximum	Unit	Condition
А	2.8	2.9		
В	2.9	3.0	\/	L-150mΛ
С	3.0	3.1	V	I _F =150mA
D	3.1	3.2		

Note for Table 6:

1. Bridgelux maintains a tolerance of \pm 0.1V on forward voltage measurements.

Product Bin Definitions

Table 7: MacAdam Ellipse Color Bin Definitions

сст	Calau Suasa	Color Space Center Point		Mainu Avin	A Consultation	Ellipse	0.1.5
001	Color Space	Х	Υ	Major Axis	Minor Axis	Rotation Angle	Color Bin
	3 SDCM	0.4578	0.4101	0.0081	0.0042	53.70	1
2700K	6 SDCM	0.4578	0.4101	0.0162	0.0084	53.70	1/A/B/C/D
	3 SDCM	0.4338	0.4030	0.00834	0.00408	53.22	1
3000K	6 SDCM	0.4338	0.4030	0.01668	0.00816	53.22	1/A/B/C/D
	3 SDCM	0.4078	0.3930	0.00834	0.00408	54.00	1
3500K	6 SDCM	0.4078	0.3930	0.01668	0.00816	54.00	1/A/B/C/D
	3 SDCM	0.3818	0.3797	0.00939	0.00402	53.72	1
4000K	6 SDCM	0.3818	0.3797	0.01878	0.00804	53.72	1/A/B/C/D
	3 SDCM	0.3447	0.3553	0.00822	0.00354	59.62	1
5000K	6 SDCM	0.3447	0.3553	0.01644	0.00708	59.62	1/A/B/C/D
.,	3 SDCM	0.3287	0.3417	0.00746	0.00320	59.09	1
5700K	6 SDCM	0.3287	0.3417	0.01492	0.00640	59.09	1/A/B/C/D
0===1/	3 SDCM	0.3123	0.3282	0.00669	0.00285	58.57	1
6500K	6 SDCM	0.3123	0.3282	0.01338	0.0057	58.57	1/A/B/C/D

Notes for Table 7:

^{1.} Color binning at T_{sp}=25°C unless otherwise specified

^{2.} Bridgelux maintains a tolerance of \pm 0.007 on x and y color coordinates in the CIE 1931 color space.

Product Bin Definitions

2700K 3000K 0.4250 0.4200 0.4150 0.4200 0.4100 E_{0.4100} E 0.4050 0.4000 1 0.4050 0.3950 0.4000 0.3950 0.3850 0.4250 0.4300 0.4350 0.4400 0.4450 0.4500 0.4500 0.4550 0.4750 0.4600 CIE x 0.4650 0.4700 CIE_x 0.4000 0.4100 4000K 3500K 0.4050 0.3900 0.4000 0.3850 E_{0.3900} E 0.3800 0.3750 0.3850 0.3700 0.3800 0.3650 0.3750 0.3950 0.4000 0.4050 0.4100 CIE_x 0.4150 0.4200 0.4250 0.4300 0.3700 0.3750 0.3800 0.3850 CIE_x 0.3900 0.3950 0.4000 0.3650 0.3750 0.3600 5000K 5700K 0.3700 0.3550 0.3650 0.3500 E_{0.3550} E 0.3450 0.3350 0.3450 0.3300 0.3400 0.3250 0.3350 0.3450 CIE x 0.3400 0.3500 0.3550 0.3600 CIE_x 0.3450 6500K 0.3400 0.3350 E 0.3300 0.3250 0.3200

0.3250

0.3200

Figure 1: C.I.E. 1931 Chromaticity Diagram (5 Color Bin Structure, Cold-color Targeted at T_{so}=25°C)

 $^{0.3100}$ CIE x $^{0.3150}$

0.3050

Performance Curves

Figure 2: Drive Current vs. Forward Voltage (T_{sp}=25°C)

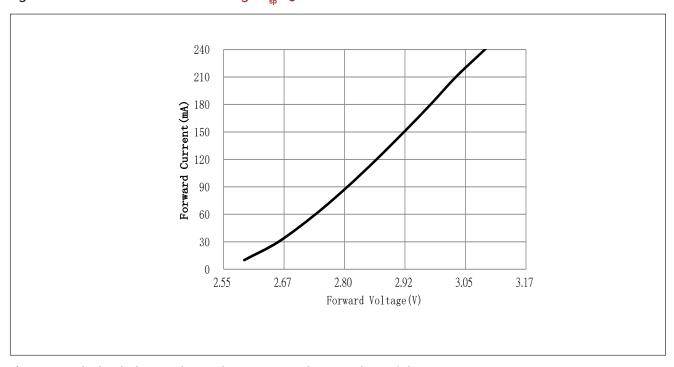
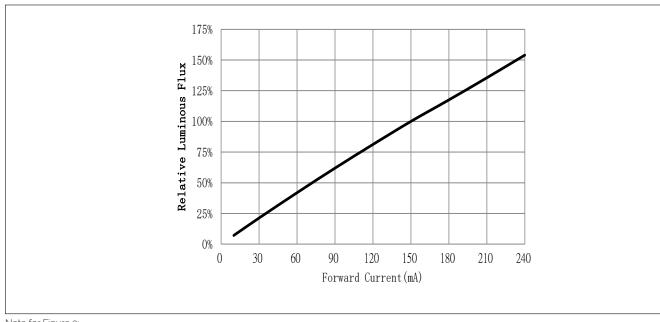


Figure 3: Typical Relative Luminous Flux vs. Forward Current ($T_{\rm sp}$ =25°C)



Note for Figure 3:

1. Pulse width modulation (PWM) is recommended for dimming effects.

Performance Curves

Figure 4: Typical Relative Flux vs. Solder Point Temperature

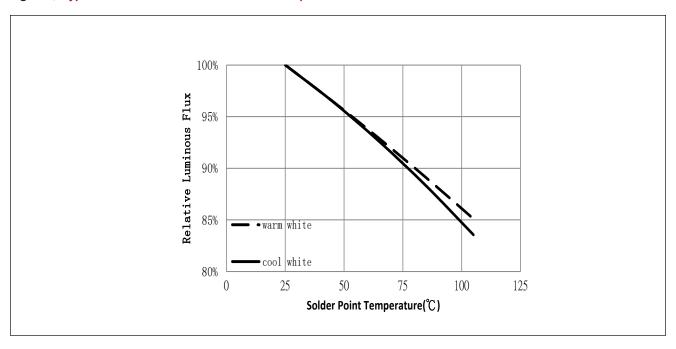
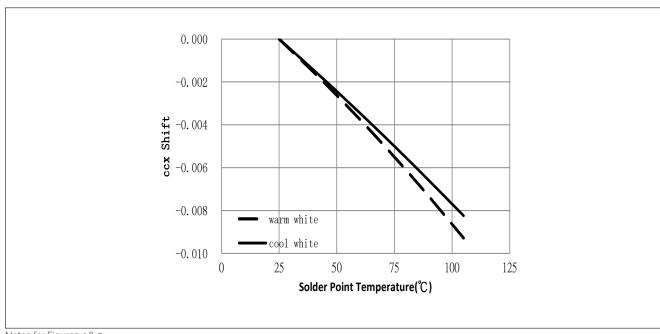


Figure 5: Typical ccx Shift vs. Solder Point Temperature



Notes for Figures 4 & 5:

- 1. Characteristics shown for warm white based on 3000K and 80 CRI.
- 2. Characteristics shown for cool white based on 5000K and 80 CRI.
- ${\it 3.} \ For other color \ SKUs, the shift in color \ will \ vary. \ Please \ contact \ your \ Bridgelux \ Sales \ Representative \ for \ more \ information.$

Performance Curves

0.000
-0.002
-0.004
-0.006
-0.008
-0.010
-0.012
0
25 50 75 100 125

Solder Point Temperature(°C)

Figure 6: Typical ccy Shift vs. Solder Point Temperature

Notes for Figure 6:

^{1.} Characteristics shown for warm white based on 3000K and 80 CRI.

^{2.} Characteristics shown for cool white based on 5000K and 80 CRI.

^{3.} For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

Typical Radiation Pattern

100% 80% Relative Intensity 60% 20% 15 -90 -75 -60 -45 -15 0 60 75 Angular Displacement (°)

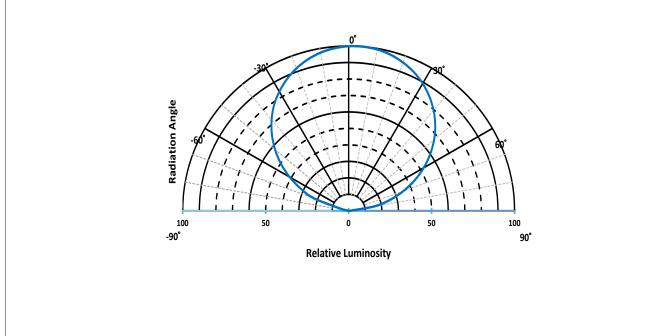
Figure 7: Typical Spatial Radiation Pattern at 150mA, T_{sp}=25°C

Figure 8: Typical Polar Radiation Pattern at 150mA, T_{sp}=25°C

Notes for Figure 7:

- 1. Typical viewing angle is 120°.
- 2. The viewing angle is defined as the off axis angle from the centerline where luminous intensity (Iv) is ½ of the peak value.

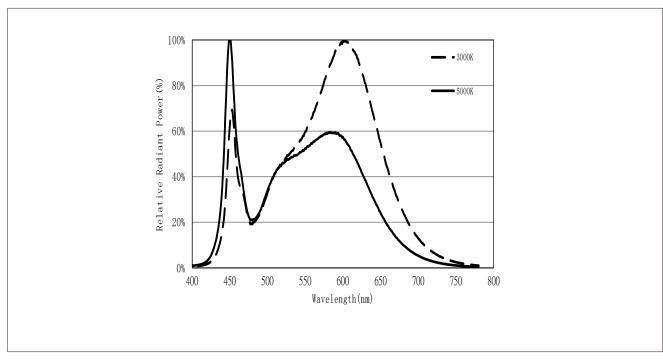




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Typical Color Spectrum

Figure 9: Typical Color Spectrum

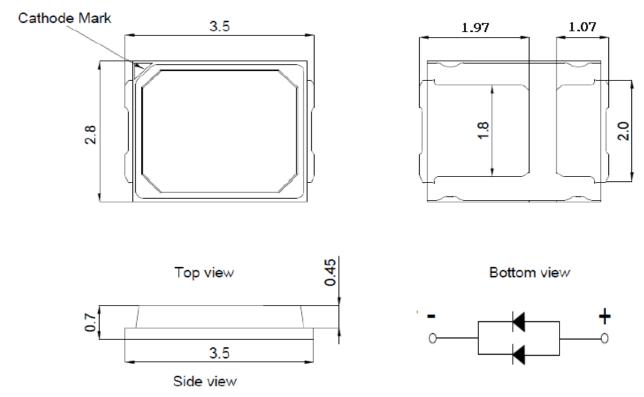


Notes for Figure 9:

- 1. Color spectra measured at nominal current for Tsp = 25°C
- 2. Color spectra shown for 80 CRI products.

Mechanical Dimensions

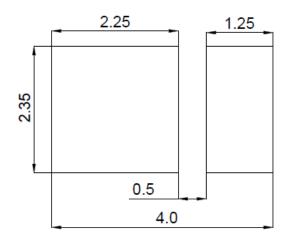
Figure 10: Drawing for SMD 2835



Notes for Figure 10:

- 1. Drawings are not to scale.
- 2. Drawing dimensions are in millimeters.
- 3. Unless otherwise specified, tolerances are ± 0.10mm.

Recommended PCB Soldering Pad Pattern



Reliability

Table 8: Reliability Test Items and Conditions

No.	ltems	Reference Standard	Test Conditions	Drive Current	Test Duration	Units Failed/Tested
1	Moisture/Reflow Sensitivity	J-STD-020E	T _{std} = 260°C, 10sec, Precondition: 60°C, 60%RH, 168hr	-	3 reflows	0/20
2	Low Temperature Storage	JESD22-A119	T _a =-40°C	-	1000 hours	0/20
3	High Temperature Storage	JESD22-A103D	T _a = 100°C	-	1000 hours	0/20
4	Low Temperature Operating Life	JESD22-A108D	T _a =-40°C	150mA	1000 hours	0/20
5	Temperature Humidity Operating Life	JESD22-A101C	T _{sp} =85°C, RH=85%	150mA	1000 hours	0/20
6	High Temperature Operating Life	JESD22-A108D	T _{sp} =105°C	240mA	1000 hours	0/20
7	Power switching	IEC62717:2014	T _{sp} = 105°C 30 sec on, 30 sec off	240mA	30000 cycles	0/20
8	Thermal Shock	JESD22-A106B	T _a =-40°C ~100°C; Dwell : 15min; Transfer: 10sec	-	200 cycles	0/20
9	Temperature Cycle	JESD22-A104E	T _a =-40°C ~100°C; Dwell at extreme temperature: 15min; Ramp rate < 105°C/min		200 cycles	0/20
10	Electrostatic Discharge	JS-001-2012	HBM, 2KV, 1.5kΩ, 100pF, Alternately positive or negative	-	-	0/20

Passing Criteria

Item	Symbol	Test Condition	Passing Criteria
Forward Voltage	Vf	150mA	ΔVf<10%
Luminous Flux	Fv	150mA	∆Fv<30%
Chromaticity Coordinates	(x, y)	150mA	Δu'v'<0.007

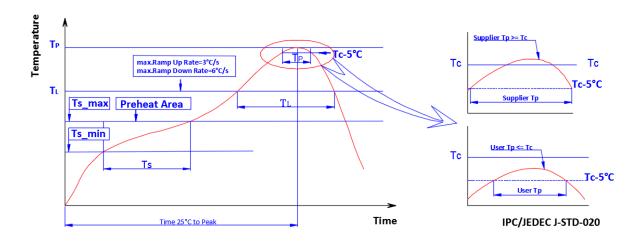
Notes for Table 8:

^{1.} Measurements are performed after allowing the LEDs to return to room temperature

^{2.} T_{std}: reflow soldering temperature; T_a: ambient temperature

Reflow Characteristics

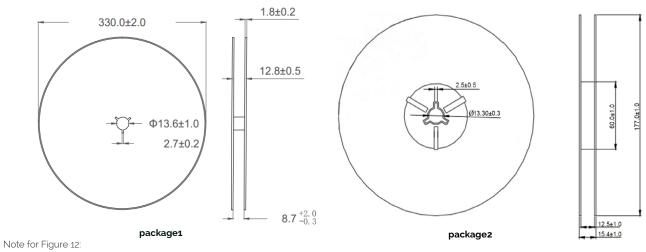
Figure 11: Reflow Profile



Profile Feature	Lead Free Assembly		
Temperature Min. (Ts_min)	160°C		
Temperature Max. (Ts_max)	205°C		
Time (ts) from Ts_min to Ts_max	60-150 seconds		
Ramp-Up Rate (TL to Tp)	3 °C/second		
Liquidus Temperature (TL)	220 °C		
Time (TL) Maintained Above TL	60-150 seconds		
Peak Temp(Tp)	260 °C max.		
Time (Tp) Within 5 °C of the Specified Classification Temperature (Tc)	25 seconds max.		
Ramp-Down Rate (Tp to TL)	5 °C/second max.		
Time 25 °C to Peak Temperature	10 minutes max.		

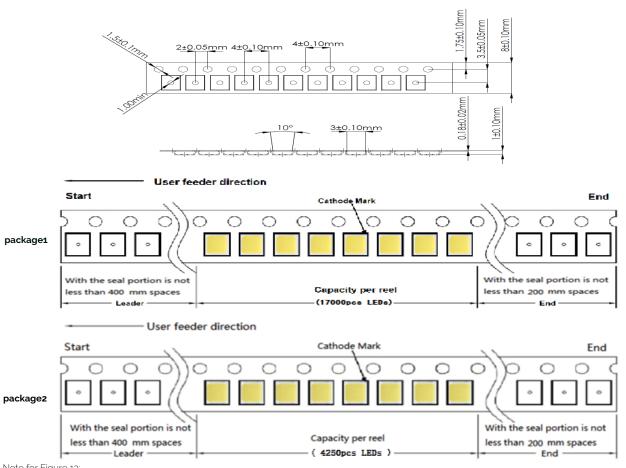
Packaging

Figure 12: Emitter Reel Drawings



1. Drawings are not to scale. Drawing dimensions are in millimeters.

Figure 13: Emitter Tape Drawings

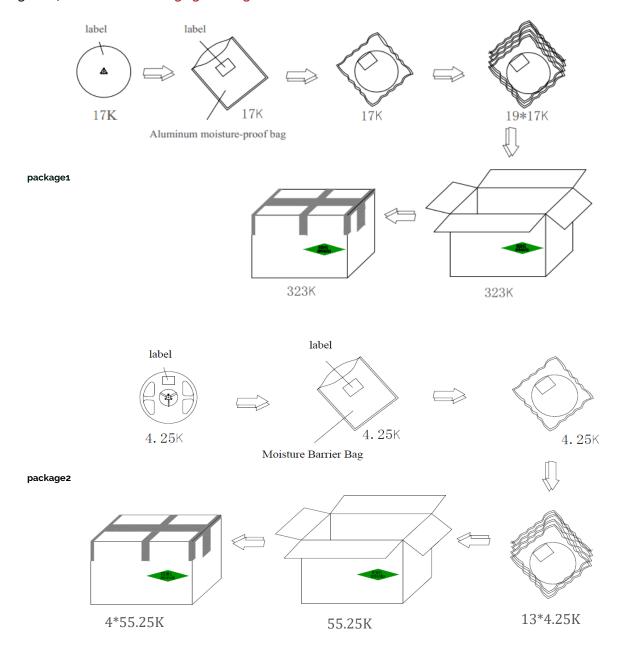


Note for Figure 13:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

Packaging

Figure 14: Emitter Reel Packaging Drawings



Note for Figure 14:

1. Drawings are not to scale.

Design Resources

Please contact your Bridgelux sales representative for assistance.

Precautions

CAUTION: CHEMICAL EXPOSURE HAZARD

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED emitter. Please consult Bridgelux Application Note AN51 for additional information.

CAUTION: EYE SAFETY

Eye safety classification for the use of Bridgelux SMD LED emitter is in accordance with IEC specification EN62471: Photobiological Safety of Lamps and Lamp Systems. SMD LED emitters are classified as Risk Group 1 when operated at or below the maximum drive current. Please use appropriate precautions. It is important that employees working with LEDs are trained to use them safely.

CAUTION: RISK OF BURN

Do not touch the SMD LED emitter during operation. Allow the emitter to cool for a sufficient period of time before handling. The SMD LED emitter may reach elevated temperatures such that could burn skin when touched.

CAUTION

CONTACT WITH LIGHT EMITTING SURFACE (LES)

Avoid any contact with the LES. Do not touch the LES of the emitter or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the emitter

Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area).

Disclaimers

MINOR PRODUCT CHANGE POLICY

The rigorous qualification testing on products offered by Bridgelux provides performance assurance. Slight cosmetic changes that do not affect form, fit, or function may occur as Bridgelux continues product optimization.

STANDARD TEST CONDITIONS

Unless otherwise stated, LED emitter testing is performed at the nominal drive current.

About Bridgelux: Bridging Light and Life™

At Bridgelux, we help companies, industries and people experience the power and possibility of light. Since 2002, we've designed LED solutions that are high performing, energy efficient, cost effective and easy to integrate. Our focus is on light's impact on human behavior, delivering products that create better environments, experiences and returns—both experiential and financial. And our patented technology drives new platforms for commercial and industrial luminaires.

For more information about the company, please visit bridgelux.com twitter.com/Bridgelux facebook.com/Bridgelux youtube.com/user/Bridgelux WeChat ID: BridgeluxInChina https://www.linkedin.com/company/bridgelux-inc-_2



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